

**IN THE CLAIMS**

Please amend the claims as follows.

1-16. (Canceled).

17. (Previously Presented) A process comprising:

forming a first via in a wire-bonding mounting substrate, wherein the wire-bonding mounting substrate includes an upper protective layer and a lower protective layer, and wherein forming proceeds from the lower protective layer toward the upper protective layer; and

    patterning a first wire-bond pad symmetrically and directly over the first via, wherein forming ceases upon contact with the first wire-bond pad.

18. (Canceled).

19. (Original) The process of claim 17, further including:

forming a via liner in the first via.

20. (Original) The process of claim 17, further including:

filling the first via with an interconnect.

21. (Original) The process of claim 17, wherein forming the first via precedes

patterning the first wire-bond pad.

22. (Original) The process of claim 17, further including:

filling the first via with an interconnect;

coupling the first via to a first bump.

23. (Original) The process of claim 17, further including:

coupling the first wire-bond pad to a first bump.

24. (Previously Presented) A method comprising:  
forming a first via in a wire-bonding mounting substrate, wherein the wire-bonding mounting substrate includes an upper protective layer and a lower protective layer, and wherein forming proceeds from the lower protective layer toward the upper protective layer;  
patterning a first wire-bond pad directly over the first via, wherein forming ceases upon contact with the first wire-bond pad; and  
coupling a die to the first wire-bond pad.
25. (Original) The method of claim 24, further including:  
forming a second via in the wire-bonding mounting substrate;  
patterning a second wire-bond pad directly over the second via; and  
coupling the die to the second wire-bond pad.
26. (Original) The method of claim 24, further including:  
filling the first via with an interconnect.
27. (Original) The method of claim 24, further including:  
filling the first via with an interconnect; and  
coupling the first via to a first bump.

28-30. (Canceled)